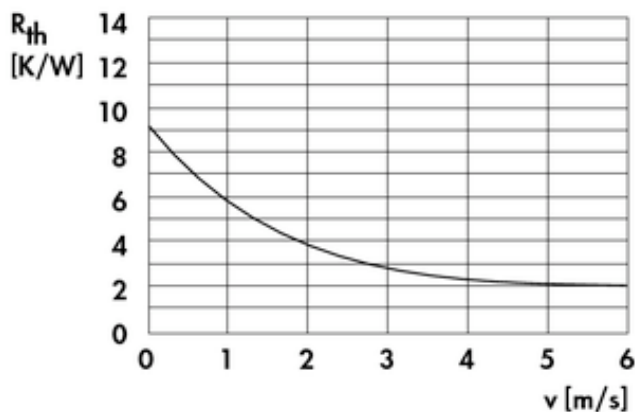
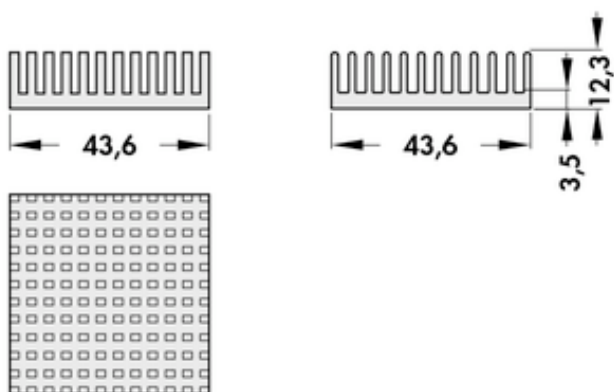
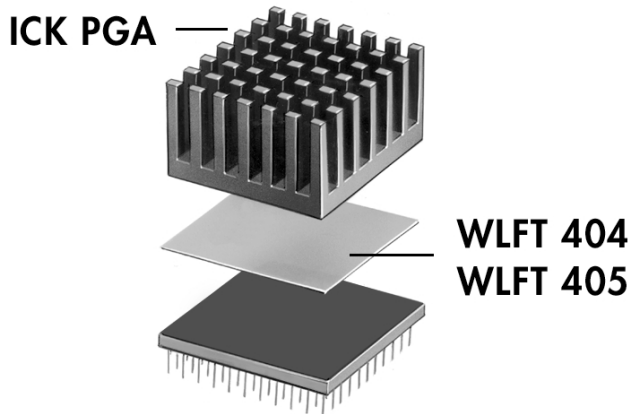


Heatsinks for PGA / **ICK PGA 17 x 17 x 12**



43,6 x 43,6 x 12,3 mm, for IC design PGA and others

**Parameters of article ICK PGA 17 x 17 x 12**

<b>R<sub>th</sub> [K/W]</b>	<b>i</b> 9
<b>dissipation loss [W]</b>	<b>i</b> 6.5
<b>mounting method</b>	therm. conductive foil / therm. cond. adhesive
<b>socket</b>	universal
<b>suitable for processor type</b>	universal
<b>width [mm]</b>	43.6
<b>height [mm]</b>	12.3
<b>plate thickness [mm]</b>	3.5
<b>length on stock [mm]</b>	43.6
<b>surface treatment</b>	black anodised

**Accessories/ related articles**

Thermally conductive foil both sides adhesive / **WLFT 404 43 x 43**

Thermally conductive foil both sides adhesive / **WLFT 405 43 x 43**